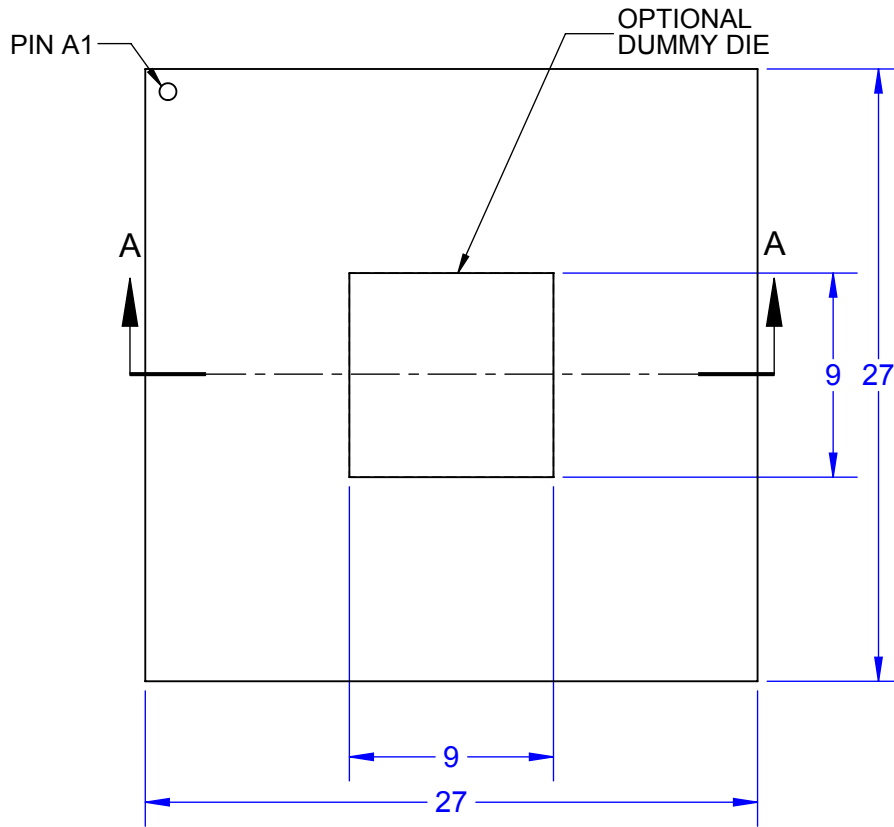
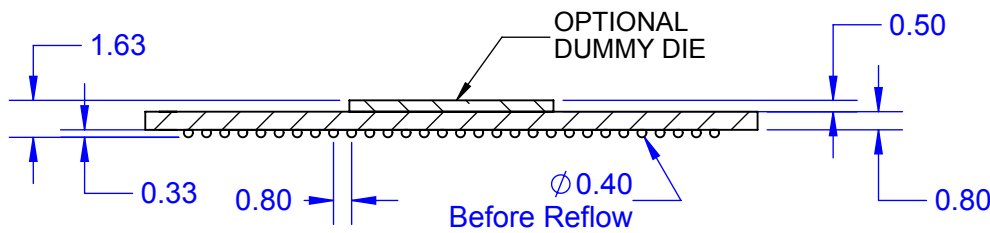
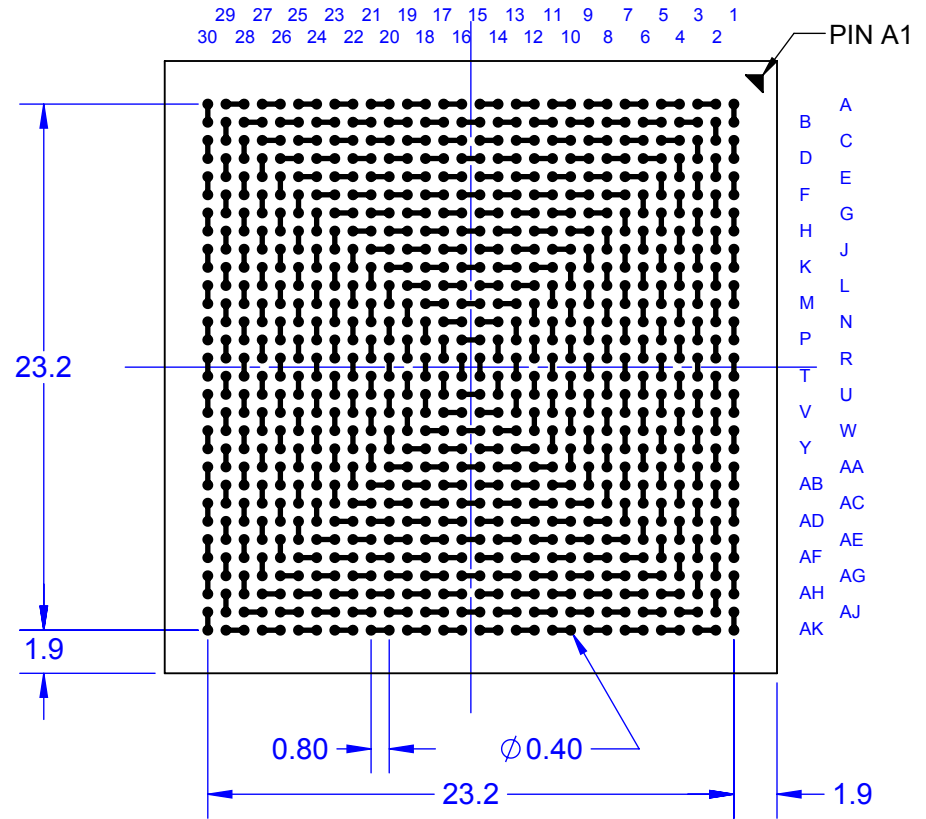


### TOP VIEW



### BALL VIEW



SECTION A-A

Notes: (Unless Otherwise Specified).

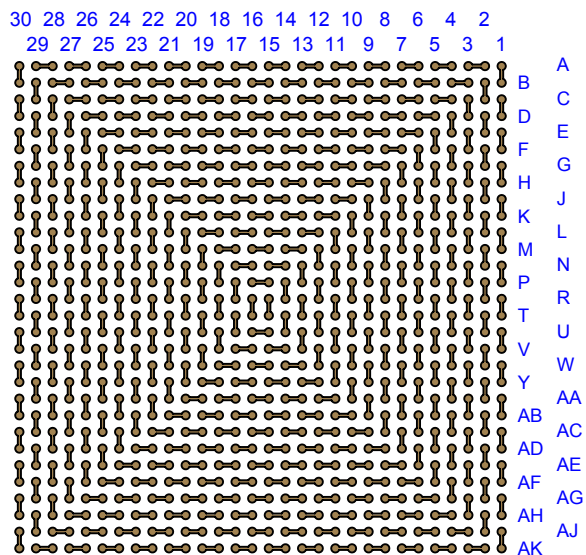
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.40mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.33mm [13 MIL].
- 5) PAD Cu DIAMETER: 0.508mm [20 MIL].
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMENDED BAKING 24 HOURS @ 125°C TO REMOVE MOISTURE PRIOR SOLDERING TO PC BOARD.

PART NUMBER TABLE

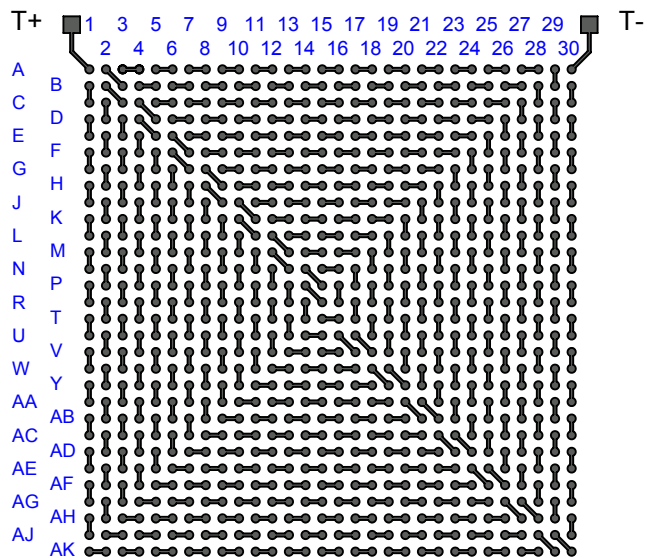
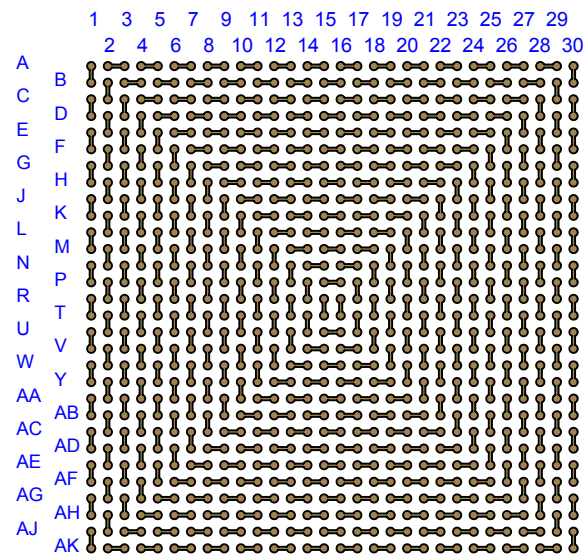
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
LBGA900T.8C-DC309	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
LBGA900T.8C-DC309-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
LBGA900T.8-DC309	Sn63/Pb37	NO	NO	NO
LBGA900T.8-DC309-D	Sn63/Pb37	NO	NO	YES

APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T.Au	04/17/15				
ENG M. Hart	04/17/15	SCALE 3:1	SIZE A	DRAWING NO. 583091	REV A
MFG		DO NOT SCALE DRAWING			SHEET 1 OF 2
QA					
CUST					
REVISED					

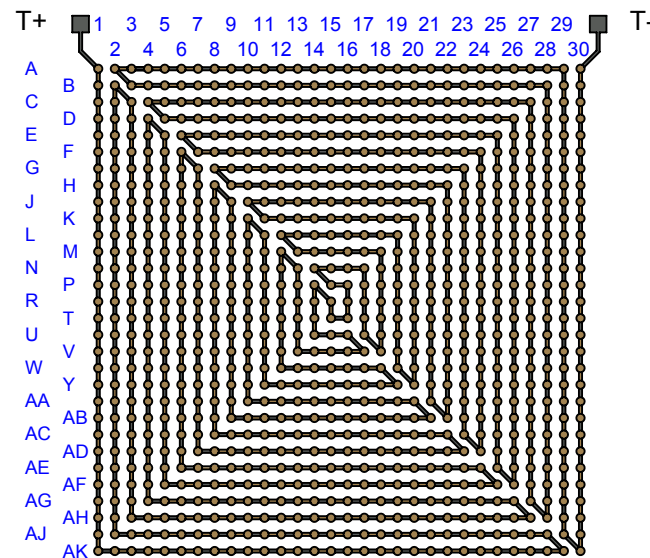
### BALL VIEW



### BOTTOM SIDE (TOP X-RAY VIEW)



**TEST VEHICLE BOARD**



**AFTER MOUNTING**

**Notes:**

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING: 0.33mm [13 MIL].

<b>TopLine®</b>			
TITLE		LBGA900T.8-DC309D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
3:1	A	583091	A
DO NOT SCALE DRAWING			SHEET 2 OF 2